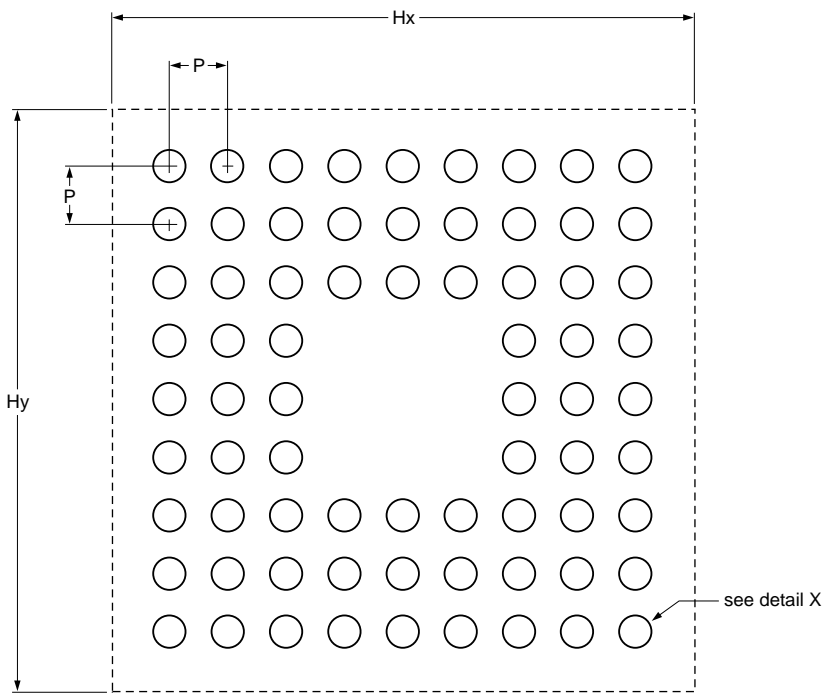





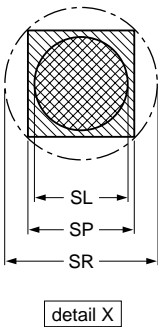
Footprint information for reflow soldering of TFBGA64 package

SOT962-3



Generic footprint pattern  
Refer to the package outline drawing for actual layout

-  solder land
-  solder paste deposit
-  solder land plus solder paste
- occupied area
- - - - - solder resist



DIMENSIONS in mm

P	SL	SP	SR	Hx	Hy
0.50	0.275	0.300	0.425	4.900	4.900